有关敝公司产品的注意事项

请务必在使用敝公司产品之前阅读。

⚠ 注意

产品目录中的记载内容

本产品目录中所记载的内容为2019年10月的内容。因产品改良等原因，可能会不经预告而变更其记载内容，或是停止供应本产品目录中所记载的产品。所以，请务必在使用前先确认最新的产品信息。

未按照本产品目录中所记载的内容或交货规格说明书使用敝公司产品，即便其致使用设备发生损害、不良情况等时，敝公司也不承担任何责任，敬请知悉。

签署交货规格说明书

就本产品目录中所记载产品的产品规格等相关内容，敝公司备有交货规格说明书，详情请向敝公司咨询。在使用敝公司产品前请务必就交货规格说明书之内容确认并批准之。

实装前的事前评估

使用敝公司产品时，请务必事先安装到使用设备之后，在实际使用的环境下进行评估和确认。

用途的限定

1. 可以使用的设备

本产品目录中所记载的产品预设为使用于一般电子设备［音像设备、办公自动化设备、家电产品、办公设备、信息通讯设备（手机、电脑等）］以及面向本产品目录或是交货规格说明书中另行注明的设备的通用性、标准性用途。

另外，面向汽车用电子设备、电信基础设施 / 工业设备、医疗设备（国际（GHTF）第一类、第二类、第三类）方面的应用，敝公司也备有预设的产品线，请参考本产品目录或是交货规格说明书的内容，使用相对应的产品。

2. 需要另行确认的设备

若考虑将本产品目录中所记载的产品使用于当产品发生故障、品质不良，或是由此引起的运转失常而可能会危及生命、身体或是财产，以及有可能给社会造成深刻影响的以下设备（不包括本产品目录或是交货规格说明书中另行注明可以使用设备）等时，请务必事先向敝公司咨询。

（1）运输用设备（汽车驱动控制设备、火车控制设备、船舶控制设备等）
（2）交通信号设备
（3）防灾 / 保安设备
（4）医疗设备（国际（GHTF）第三类）
（5）高公共性信息通讯设备 / 信息处理设备（电话交换机、电话 / 无线 / 广播电视基站等）
（6）其他与上述设备有同等品质与可靠性要求的设备

3. 禁止使用的设备

请勿将敝公司产品使用于对安全性和可靠性有着极高要求的以下设备。

（1）航天设备（人工卫星、火箭等）
（2）航空设备 (注释1)
（3）医疗设备（国际（GHTF）第四类）、植体（体内植入型）医疗设备 (注释2)
（4）发电控制设备（面向核能 / 水力 / 火力发电厂等的设备）
（5）海底设备（海底中继设备、海中的作业设备等）
（6）军事设备
（7）其他与上述设备有同等品质与可靠性要求的设备

注释1：仅限于对航空设备的安全运行不产生直接干扰的设备［机内娱乐设备、机内照明设备、电动座椅、餐饮设备等］，在满足敝公司另行指定的相关条件时，亦可将敝公司产品用于以上用途。在贵公司考虑将敝公司的产品用于以上用途时，请务必事先向敝公司咨询相关的信息。

注释2：包括注入人体内的部分和与此相连接的体外部分。

4. 责任的限制

未经敝公司的事先书面同意，把本产品目录中所记载的产品使用于非敝公司预设用途的设备、前述需要向敝公司咨询的设备或敝公司禁止使用的设备，从而给客户或第三方造成损害的，敝公司不承担任何责任，敬请知悉。

安全设计

需将敝公司的产品使用于对安全性和可靠性要求较高的设备、电路上时，请进行充分的安全性评估和可靠性评估。另外，请通过设置保护电路、保护装置的系统，设置冗余电路不会被单一故障影响安全性的系统等失效导向安全（fail-safe）设计，确保充分的安全性。

有关知识产权

本产品目录中所记载的信息是用于说明相关产品的典型操作以及相关应用。此类信息的使用不代表对于敝公司以及第三方的知识产权以及其他权利的使用许可或是不侵权保证。

保证范围

敝公司产品的保证范围仅限于已经交付的敝公司产品本身，由敝公司产品的故障或不良情况所诱发的损害，敝公司不承担任何责任，敬请知悉。但是，以书面形式另行签署了交易基本合同书、品质保证协定书等时，敝公司将根据该合同的条件提供保证。

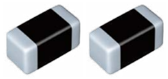
正规销售渠道

本产品目录中所记载的内容适用于从敝公司营业所、销售子公司、销售代理店（即“正规销售渠道”）购买的敝公司产品，并不适用于从其他渠道购买的敝公司产品，敬请知悉。

出口时的注意事项

本产品目录中所记载的部分产品在出口时须事先确认《外汇和对外贸易法》以及美国在出口管理方面的相关法规，并办理相关手续。如有不明之处，请向敝公司咨询。

电源用片状磁珠电感器(FB 系列 M 型)



波峰焊 回流焊

■型号标示法

※使用温度范围: -40～+125℃ (包含产品本身发热)

F B	△	M	J	3 2 1 6	H S	8 0 0	—	T	△
①		②	③	④	⑤	⑥	⑦	⑧	⑨

△＝空格

①类型

代码	类型
FB	铁氧体磁珠电感器

②外型

代码	外型
M	矩形

③特性

代码	特性
J	标准品
H	高阻抗品

④尺寸 (L×W)

代码	外型 (inch)	尺寸 (L×W) [mm]
1608	1608(0603)	1.6×0.8
2125	2125(0805)	2.0×1.25
2012	2012(0805)	
2016	2016(0806)	2.0×1.6
3216	3216(1206)	3.2×1.6
3225	3225(1210)	3.2×2.5
4516	4516(1806)	4.5×1.6
4525	4525(1810)	4.5×2.5
4532	4532(1812)	4.5×3.2

⑤材料

代码	材料
HS	材料不同时, 阻抗值也有所变化。
HM	
HL	

⑥标称阻抗值

代码 (例)	标称阻抗值 [Ω]
330	33
221	220
102	1000

⑦阻抗值公差

代码	公差
—	±25%
N	±30%

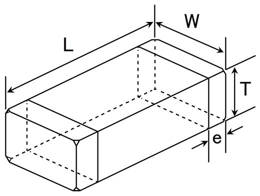
⑧包装

代码	包装
T	卷盘带装

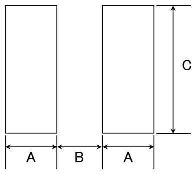
⑨本公司管理记号

代码	本公司管理记号
△	标准品

■标准外型尺寸 / 标准数量



推荐焊盘图案
实装上的注意
・请确认实装状态后使用。



Type	A	B	C
FB MJ1608	1.0	1.0	1.0
FB MJ2125	1.4	1.2	1.65
FB MJ3216	1.4	2.2	2.0
FB MJ4516	1.75	3.5	2.0
FB MH1608	1.0	1.0	1.0
FB MH2012	1.4	1.2	1.65
FB MH2016	1.4	1.2	2.0
FB MH3216	1.4	2.2	2.0
FB MH3225	1.4	2.2	2.9
FB MH4516	1.75	3.5	2.0
FB MH4525	1.75	3.5	2.9
FB MH4532	1.75	3.5	3.7

单位: mm

Type	L	W	T	e	标准数量 [pcs]	
					纸带	压纹带
FB MJ1608 (0603)	1.6±0.2 (0.063±0.008)	0.8±0.2 (0.031±0.008)	0.8±0.2 (0.031±0.008)	0.3±0.2 (0.012±0.008)	4000	—
FB MJ2125 (0805)	2.0±0.2 (0.079±0.008)	1.25±0.2 (0.049±0.008)	0.85±0.2 (0.033±0.008)	0.5±0.3 (0.020±0.012)	4000	—
FB MJ3216 (1206)	3.2±0.3 (0.126±0.012)	1.6±0.2 (0.063±0.008)	1.1±0.2 (0.043±0.008)	0.5±0.3 (0.020±0.012)	—	2000
FB MJ4516 (1806)	4.5±0.3 (0.177±0.012)	1.6±0.2 (0.063±0.008)	1.1±0.2 (0.043±0.008)	0.5±0.3 (0.020±0.012)	—	2000
FB MH1608 (0603)	1.6±0.1 (0.063±0.004)	0.8±0.1 (0.031±0.004)	0.8±0.1 (0.031±0.004)	0.3±0.15 (0.012±0.006)	4000	—
FB MH2012 (0805)	2.0±0.2 (0.079±0.008)	1.25±0.2 (0.049±0.008)	0.85±0.2 (0.033±0.008)	0.5±0.3 (0.020±0.012)	4000	—
FB MH2016 (0806)	2.0±0.2 (0.079±0.008)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	0.5±0.3 (0.020±0.012)	—	2000
FB MH3216 (1206)	3.2±0.3 (0.126±0.012)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	0.5±0.3 (0.020±0.012)	—	2000
FB MH3225 (1210)	3.2±0.3 (0.126±0.012)	2.5±0.3 (0.098±0.012)	2.5±0.3 (0.098±0.012)	0.5±0.3 (0.020±0.012)	—	1000
FB MH4516 (1806)	4.5±0.3 (0.177±0.012)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	0.5±0.3 (0.020±0.012)	—	2000
FB MH4525 (1810)	4.5±0.4 (0.177±0.016)	2.5±0.3 (0.098±0.012)	2.5±0.3 (0.098±0.012)	0.9±0.6 (0.035±0.024)	—	1000
FB MH4532 (1812)	4.5±0.4 (0.177±0.016)	3.2±0.3 (0.126±0.012)	3.2±0.3 (0.126±0.012)	0.9±0.6 (0.035±0.024)	—	2000

单位: mm (inch)

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■型号一览

标准品

●FB MJ1608

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MJ1608HS280NT	RoHS	28	±30%	100	0.007	4.0	0.8 ±0.2
FB MJ1608HM230NT	RoHS	23	±30%	100	0.007	4.0	0.8 ±0.2

●FB MJ2125

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MJ2125HS250NT	RoHS	25	±30%	100	0.004	6.0	0.85 ±0.2
FB MJ2125HS420-T	RoHS	42	±25%	100	0.008	4.0	0.85 ±0.2
FB MJ2125HM210NT	RoHS	21	±30%	100	0.004	6.0	0.85 ±0.2
FB MJ2125HM330-T	RoHS	33	±25%	100	0.008	4.0	0.85 ±0.2
FB MJ2125HL8R0NT	RoHS	8	±30%	100	0.008	4.0	0.85 ±0.2

●FB MJ3216

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MJ3216HS480NT	RoHS	48	±30%	100	0.005	6.0	1.1 ±0.2
FB MJ3216HS800-T	RoHS	80	±25%	100	0.010	4.0	1.1 ±0.2
FB MJ3216HM380NT	RoHS	38	±30%	100	0.005	6.0	1.1 ±0.2
FB MJ3216HM600-T	RoHS	60	±25%	100	0.010	4.0	1.1 ±0.2
FB MJ3216HL160NT	RoHS	16	±30%	100	0.012	4.0	1.1 ±0.2

●FB MJ4516

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MJ4516HS720NT	RoHS	72	±30%	100	0.007	6.0	1.1 ±0.2
FB MJ4516HS111-T	RoHS	110	±25%	100	0.014	4.0	1.1 ±0.2
FB MJ4516HM560NT	RoHS	56	±30%	100	0.007	6.0	1.1 ±0.2
FB MJ4516HM900-T	RoHS	90	±25%	100	0.014	4.0	1.1 ±0.2
FB MJ4516HL230NT	RoHS	23	±30%	100	0.014	3.5	1.1 ±0.2

高阻抗品（GHz帯）

●FB MH1608

型号	EHS	阻抗值 测试频率 100 [MHz]		阻抗值 测试频率 1 [GHz]		直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
		（Ω）	公差	（Ω）	公差			
FB MH1608HM470-T	RoHS	47	±25%	75	±40%	0.020	3.5	0.8 ±0.1
FB MH1608HM600-T	RoHS	60	±25%	100	±40%	0.025	3.0	0.8 ±0.1
FB MH1608HM101-T	RoHS	100	±25%	170	±40%	0.035	2.5	0.8 ±0.1
FB MH1608HM151-T	RoHS	150	±25%	270	±40%	0.050	2.1	0.8 ±0.1
FB MH1608HM221-T	RoHS	220	±25%	370	±40%	0.070	1.8	0.8 ±0.1
FB MH1608HM331-T	RoHS	330	±25%	520	±40%	0.130	1.2	0.8 ±0.1
FB MH1608HM471-T	RoHS	470	±25%	750	±40%	0.150	1.0	0.8 ±0.1
FB MH1608HM601-T	RoHS	600	±25%	900	±40%	0.170	0.9	0.8 ±0.1
FB MH1608HM102-T	RoHS	1000	±25%	1200	±40%	0.350	0.6	0.8 ±0.1
FB MH1608HL300-T	RoHS	30	±25%	120	±40%	0.028	2.6	0.8 ±0.1
FB MH1608HL600-T	RoHS	60	±25%	220	±40%	0.045	2.1	0.8 ±0.1
FB MH1608HL121-T	RoHS	120	±25%	540	±40%	0.130	1.2	0.8 ±0.1
FB MH1608HL221-T	RoHS	220	±25%	950	±40%	0.170	0.9	0.8 ±0.1
FB MH1608HL331-T	RoHS	330	±25%	1200	±40%	0.210	0.8	0.8 ±0.1
FB MH1608HL471-T	RoHS	470	±25%	1500	±40%	0.350	0.6	0.8 ±0.1
FB MH1608HL601-T	RoHS	600	±25%	1800	±40%	0.450	0.5	0.8 ±0.1

高阻抗品

●FB MH2012

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH2012HM800-T	RoHS	80	±25%	100	0.025	2.7	0.85 ±0.2
FB MH2012HM121-T	RoHS	120	±25%	100	0.032	2.5	0.85 ±0.2
FB MH2012HM221-T	RoHS	220	±25%	100	0.060	2.0	0.85 ±0.2
FB MH2012HM331-T	RoHS	330	±25%	100	0.080	1.8	0.85 ±0.2

●FB MH2016

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH2016HM121NT	RoHS	120	±30%	100	0.015	4.5	1.6 ±0.2
FB MH2016HM251NT	RoHS	250	±30%	100	0.050	2.0	1.6 ±0.2

●FB MH3216

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH3216HM221NT	RoHS	220	±30%	100	0.020	4.0	1.6 ±0.2
FB MH3216HM501NT	RoHS	500	±30%	100	0.070	2.0	1.6 ±0.2

●FB MH3225

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH3225HM601NT	RoHS	600	±30%	100	0.042	3.0	2.5 ±0.3
FB MH3225HM102NT	RoHS	1000	±30%	100	0.100	2.0	2.5 ±0.3
FB MH3225HM202NT	RoHS	2000	±30%	100	0.130	1.2	2.5 ±0.3

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■型号一览

●FB MH4516

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH4516HM851NT	RoHS	850	±30%	100	0.100	1.5	1.6 ±0.2

●FB MH4525

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH4525HM102NT	RoHS	1000	±30%	100	0.060	3.0	2.5 ±0.3
FB MH4525HM162NT	RoHS	1600	±30%	100	0.130	2.0	2.5 ±0.3

●FB MH4532

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MH4532HM681-T	RoHS	680	±25%	100	0.028	4.0	3.2 ±0.3
FB MH4532HM132-T	RoHS	1300	±25%	100	0.060	3.0	3.2 ±0.3
FB MH4532HM202-T	RoHS	2000	±25%	100	0.130	1.3	3.2 ±0.3

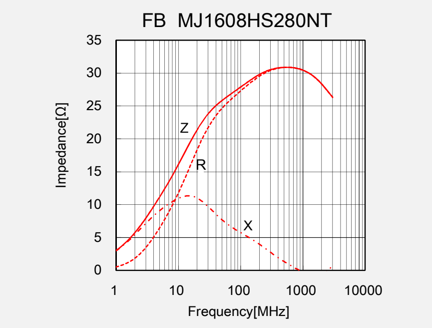
●高电流型

型号	EHS	阻抗值 [Ω]	阻抗值公差	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	厚度 [mm]
FB MJ1608HS220NTR	RoHS	22	±30%	100	0.004	7.5	0.8 ±0.2
FB MJ1608HS280NTR	RoHS	28	±30%	100	0.006	6.0	0.8 ±0.2
FB MJ1608HM180NTR	RoHS	18	±30%	100	0.004	7.5	0.8 ±0.2
FB MJ1608HM230NTR	RoHS	23	±30%	100	0.006	6.0	0.8 ±0.2

特性图

标准品

FB MJ1608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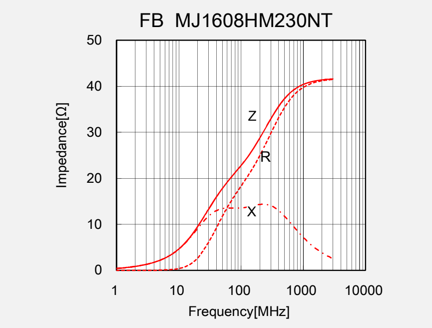
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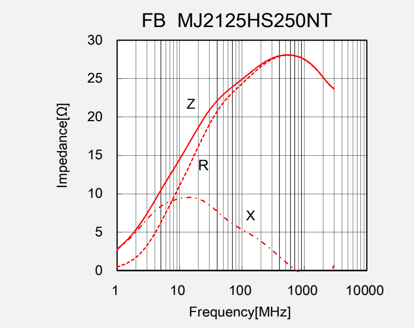
FB MJ2125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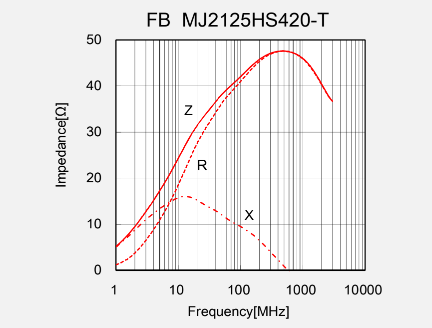
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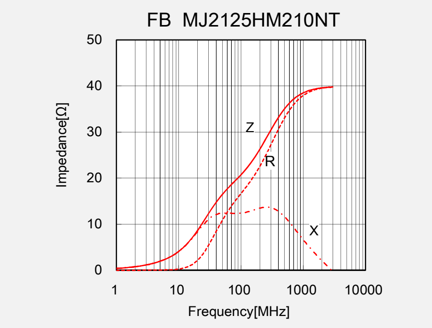
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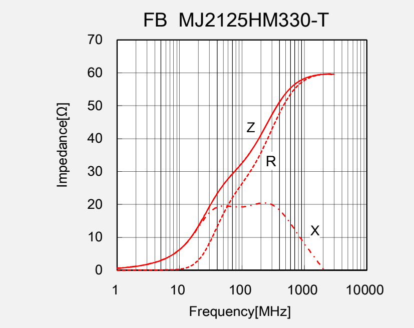
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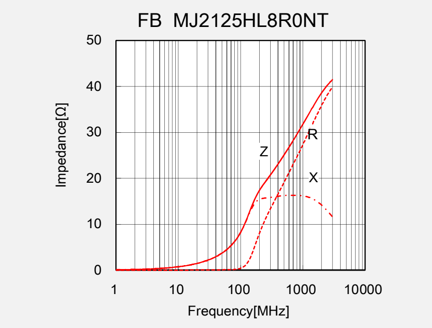
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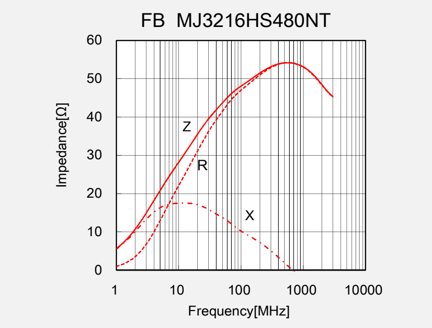
FB MJ3216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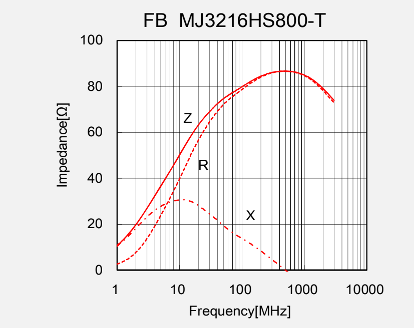
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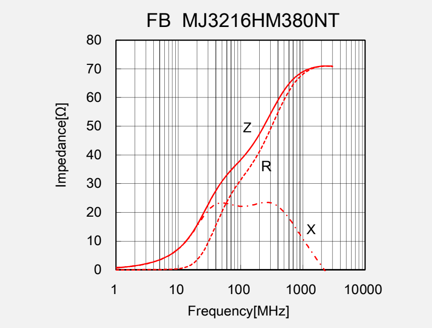
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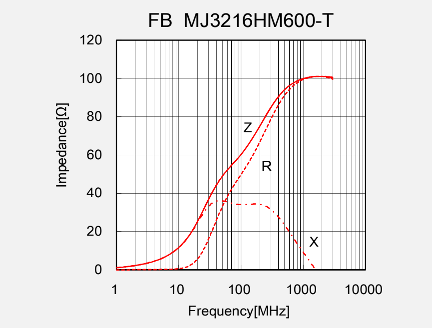
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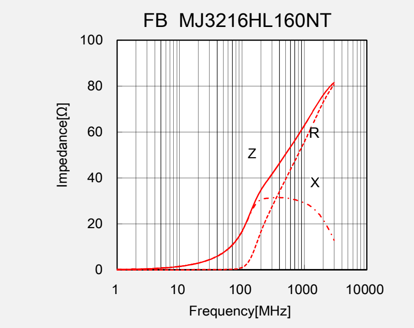
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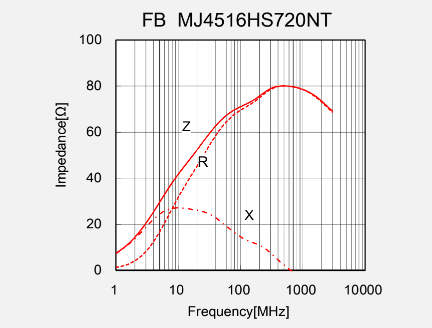
FB MJ4516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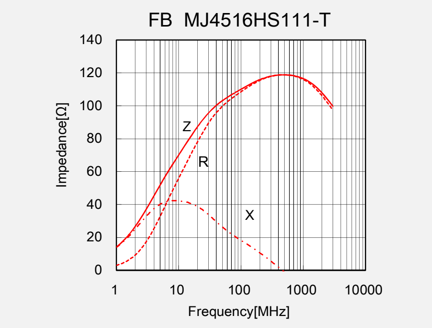
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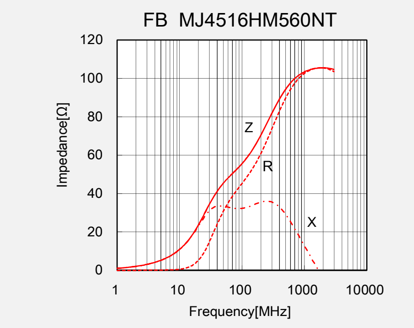
FB MJ4516HM560NT

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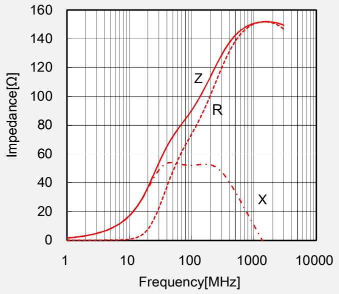
特性图

FB MJ4516HM900-T



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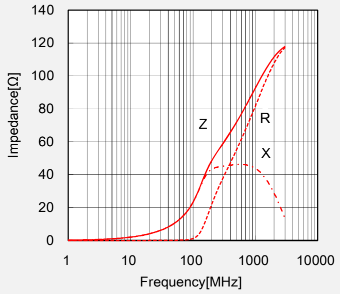
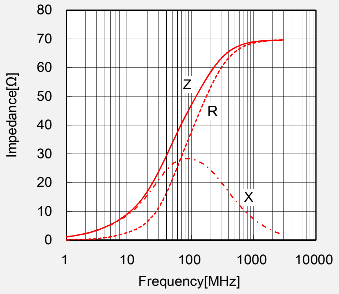


高阻抗品（GHz帯）

FB MH1608

FB MH1608HM470-T



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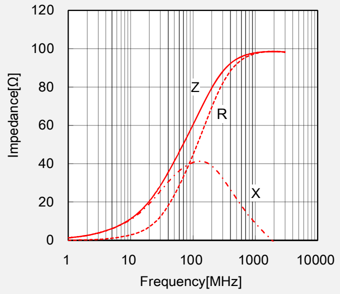

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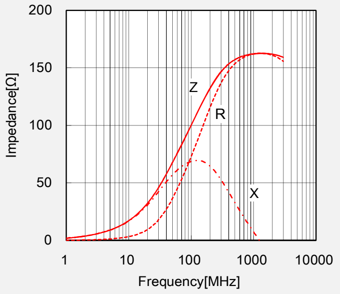

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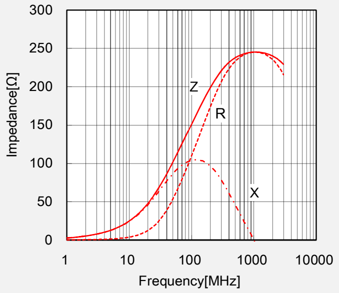

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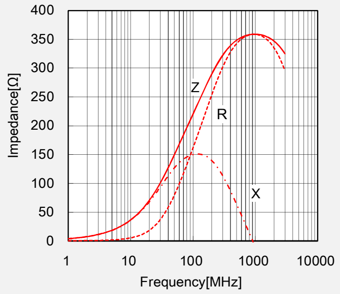

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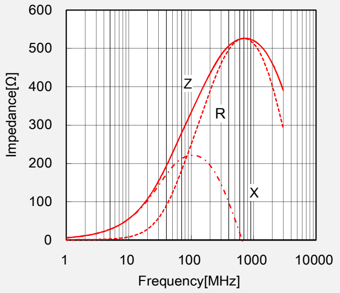

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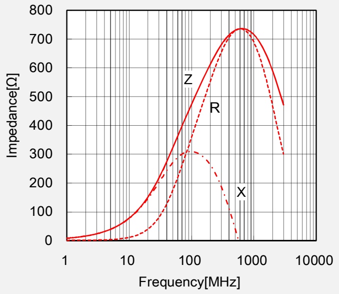

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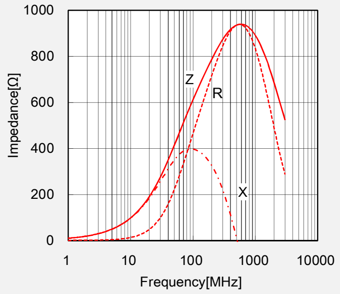

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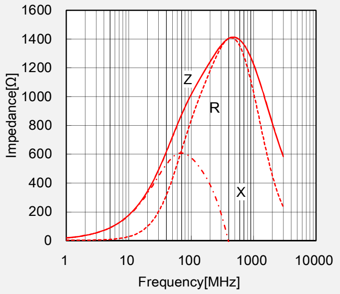
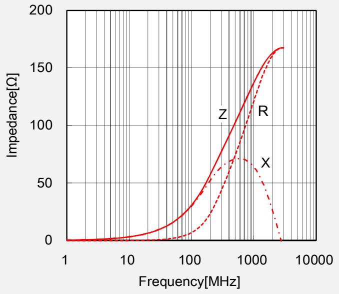
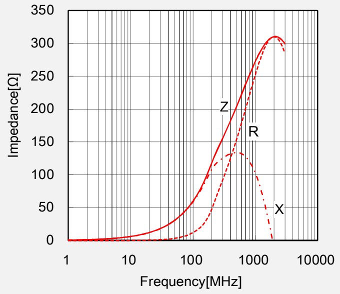


FB MH1608HL300-T



FB MH1608HL600-T



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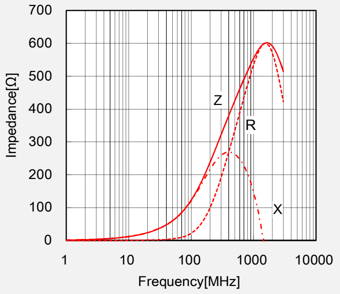

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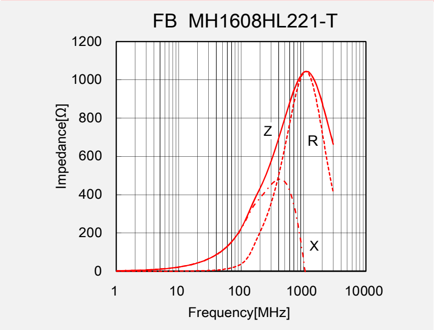
特性图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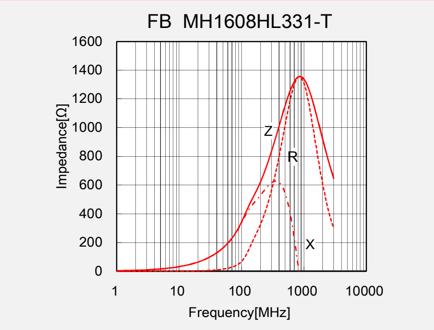
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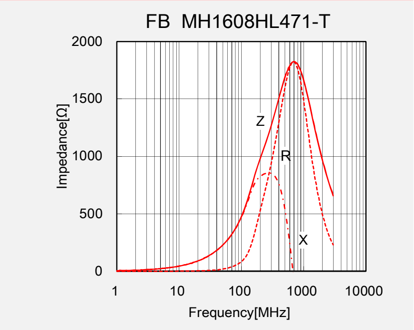
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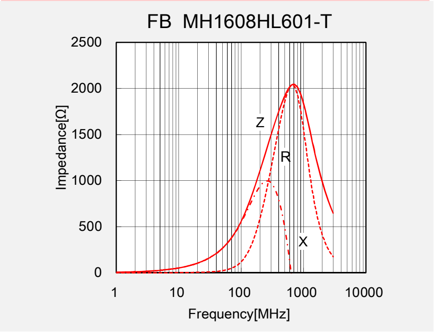
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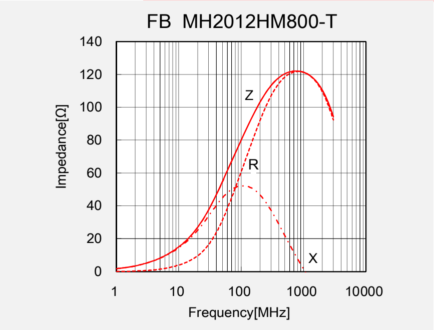
高阻抗品

FB MH2012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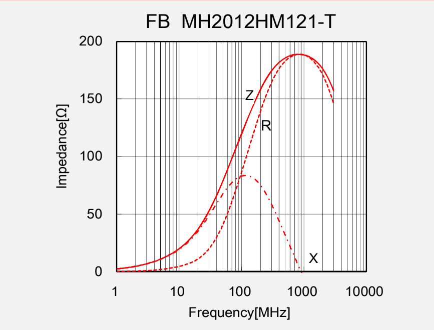
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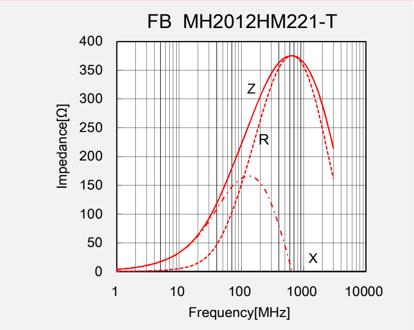
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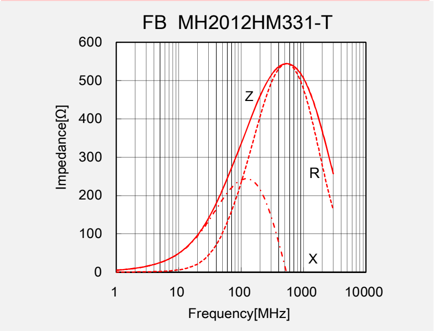
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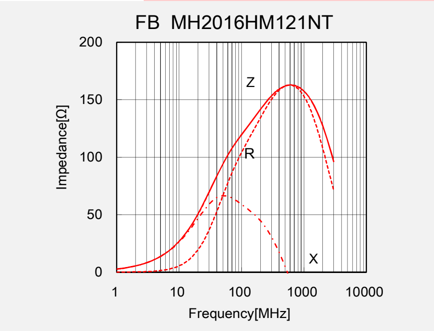
FB MH2016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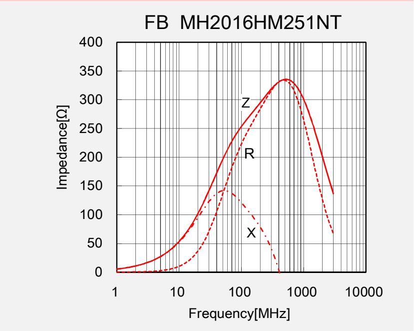
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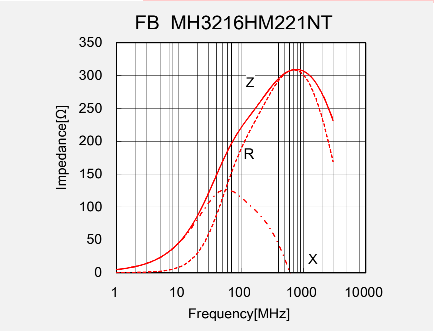
FB MH3216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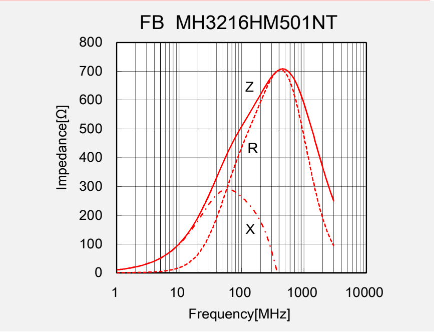
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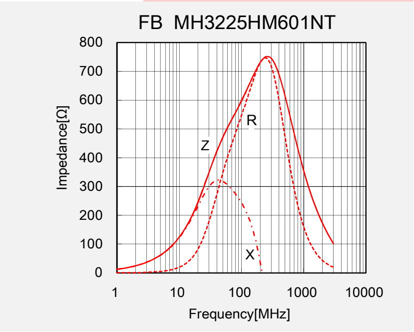
FB MH3225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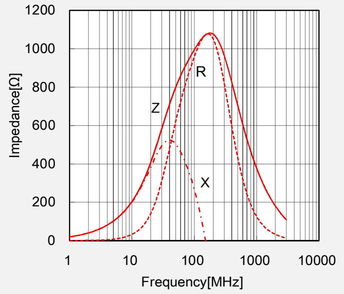
特性图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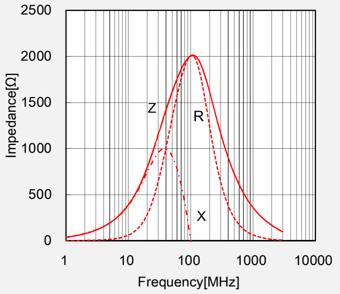
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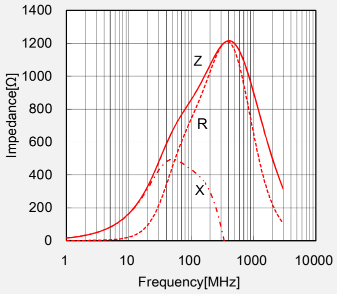
FB MH4516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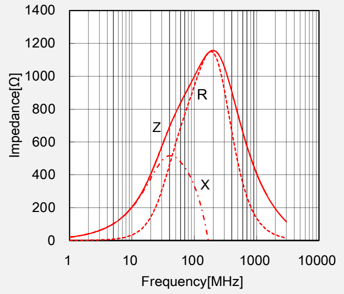
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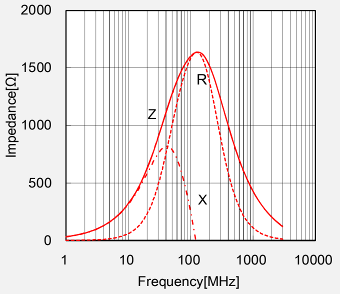
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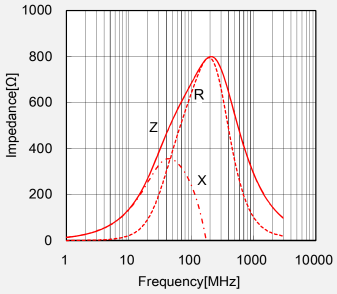
FB MH4532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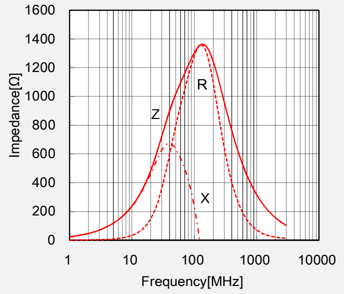
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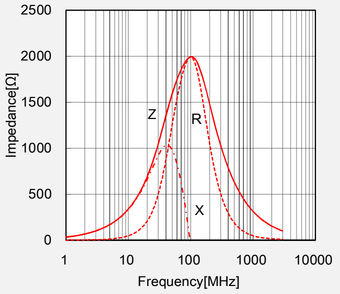
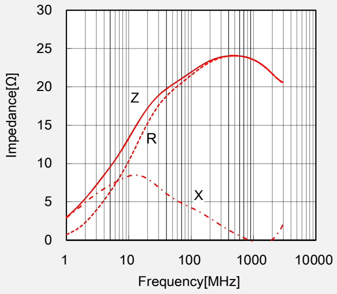

FB MH4532HM202-T

高电流型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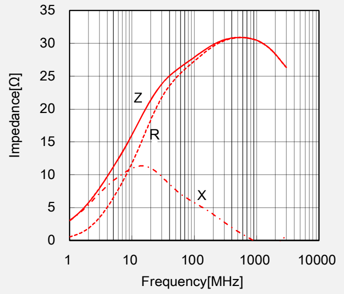
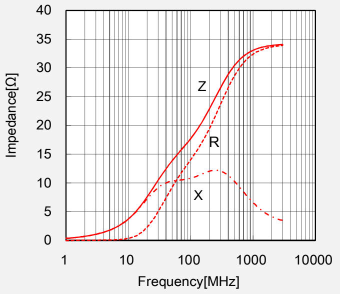

FB MJ1608HS280NTR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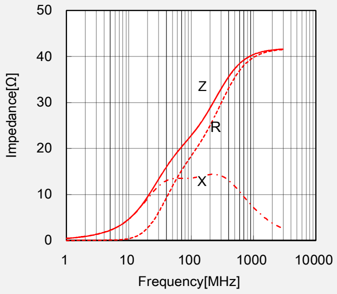
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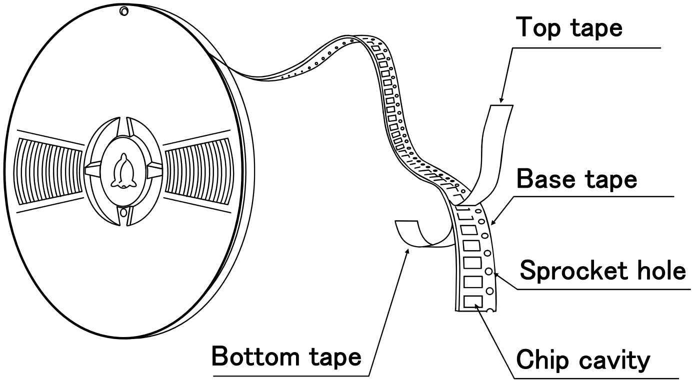
PACKAGING

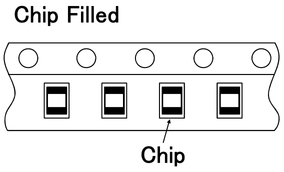
①Minimum Quantity

Type	Standard Quantity[pcs]	
	Paper Tape	Embossed Tape
1608(0603)	4000	—
2125(0805)	4000	—
2012(0805)	4000	—
2016(0806)	—	2000
3216(1206)	—	2000
3225(1210)	—	1000
4516(1806)	—	2000
4525(1810)	—	1000
4532(1812)	—	2000

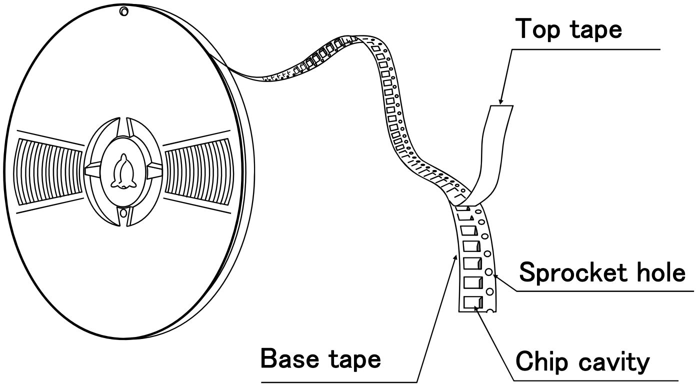
②Tape Material

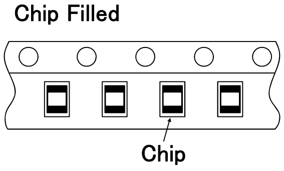
Card board carrier tape





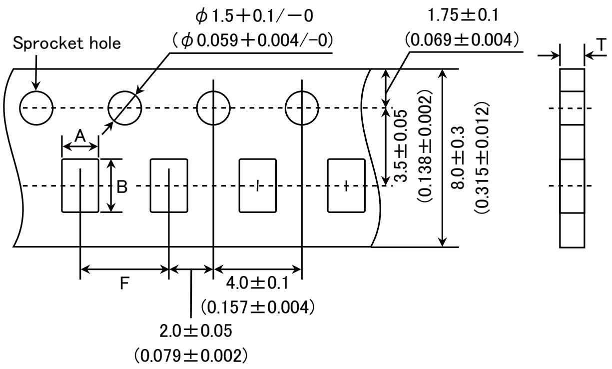
Embossed tape





③Taping Dimensions

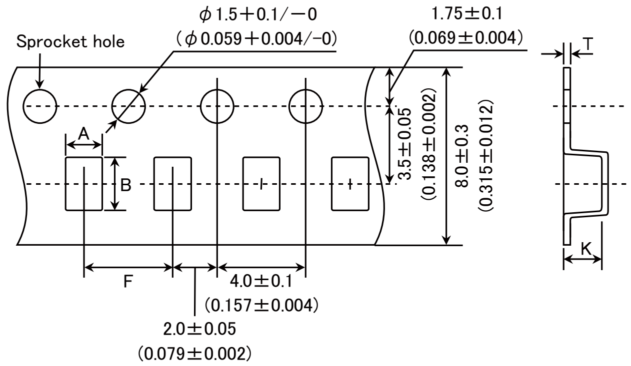
Paper tape (0.315 inches wide)



Type	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B	F	T
FB MJ1608 FB MH1608 FB TH1608 (0603)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)
FB MJ2125 FB MH2012 (0805)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)

Unit : mm(inch)

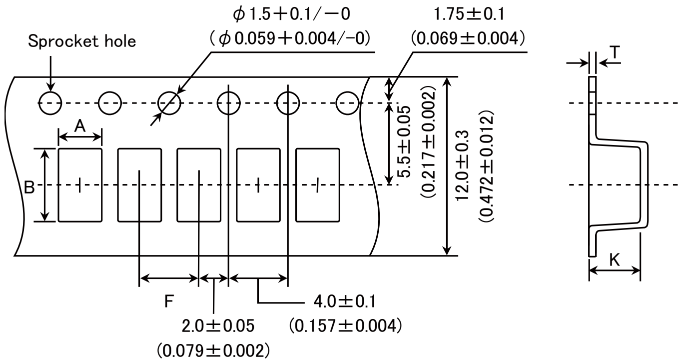
●Embossed tape (0.315 inches wide)



Type	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
FB MH2016 (0806)	1.8±0.2 (0.071±0.008)	2.2±0.2 (0.087±0.008)	4.0±0.2 (0.157±0.008)	2.6max (0.102max)	0.6max (0.024max)
FB MJ3216 (1206)	1.9±0.2 (0.075±0.008)	3.5±0.2 (0.138±0.008)	4.0±0.2 (0.157±0.008)	1.5max (0.059max)	0.3max (0.012max)
FB MH3216 (1206)	1.9±0.2 (0.075±0.008)	3.5±0.2 (0.138±0.008)	4.0±0.2 (0.157±0.008)	2.6max (0.102max)	0.6max (0.024max)
FB MH3225 (1210)	2.8±0.2 (0.110±0.008)	3.5±0.2 (0.138±0.008)	4.0±0.2 (0.157±0.008)	4.0max (0.157max)	0.6max (0.024max)

Unit : mm(inch)

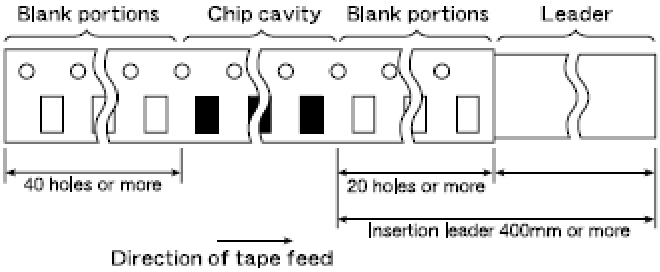
●Embossed tape (0.472 inches wide)



Type	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
FB MJ4516 (1806)	1.9±0.2 (0.075±0.008)	4.9±0.2 (0.193±0.008)	4.0±0.2 (0.157±0.008)	1.5max (0.059max)	0.3max (0.012max)
FB MH4516 (1806)	1.9±0.2 (0.075±0.008)	4.9±0.2 (0.193±0.008)	4.0±0.2 (0.157±0.008)	2.6max (0.102max)	0.6max (0.024max)
FB MH4525 (1810)	2.9±0.2 (0.114±0.008)	4.9±0.2 (0.193±0.008)	4.0±0.2 (0.157±0.008)	4.0max (0.157max)	0.6max (0.024max)
FB MH4532 (1812)	3.6±0.2 (0.142±0.008)	4.9±0.2 (0.193±0.008)	8.0±0.2 (0.315±0.008)	4.0max (0.157max)	0.6max (0.024max)

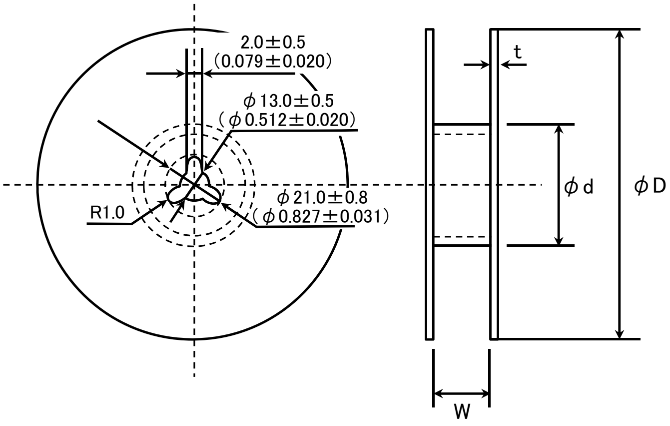
Unit : mm(inch)

④Leader and Blank portion



Insertion leader is 400 mm or more (including 20 empty cavities)
Empty cavities at end of reel : 40 holes or more

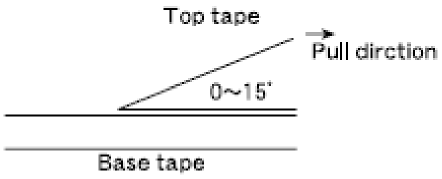
⑤Reel size



Type	ϕD	ϕd	W	t
FB MJ1608	180+0/−3 (7.09+0/−0.118)	60+1/−0 (2.36+0.039/−0)	10.0±1.5 (0.394±0.059)	2.5max (0.098max)
FB MJ2125				
FB MJ3216				
FB MJ4516			14.0±1.5 (0.551±0.059)	
FB MH1608			10.0±1.5 (0.394±0.059)	
FB MH2012				
FB MH2016				
FB MH3216				
FB MH3225				
FB MH4516			14.0±1.5 (0.551±0.059)	
FB MH4525				
FB MH4532	330±2.0 (12.99±0.080)	100±1.0 (3.94±0.039)	14.0±2.0 (0.551±0.080)	3.0max (1.181max)
FB TH1608	180+0/−3 (7.09+0/−0.118)	60+1/−0 (2.36+0.039/−0)	10.0±1.5 (0.394±0.059)	2.5max (0.098max)

Unit : mm(inch)

⑥Top tape strength



The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.

CHIP BEAD INDUCTORS FOR POWER LINE (FB SERIES M TYPE)

■RELIABILITY DATA

1. Operating Temperature Range

Specified Value	－40℃～＋125℃ Including self-generated heat

2. Storage Temperature Range

Specified Value	－40℃～＋85℃
Test Methods and Remarks	*Note: -5 to ＋40℃ in taped packaging

3. Impedance

Specified Value	Within the specified tolerance
Test Methods and Remarks	Measuring equipment : Impedance analyzer (HP4291A) or its equivalent Measuring frequency : 100±1 MHz

4. DC Resistance

Specified Value	Within the specified range
Test Methods and Remarks	Four-terminal method Measuring equipment : Milliohm High-Tester 3226 (Hioki Denki) or its equivalent

5. Rated Current

Specified Value	Within the specified range

6. Vibration

Specified Value	Appearance : No significant abnormality Impedance change : Within ±30% of the initial value
Test Methods and Remarks	According to JIS C60068-2-6. Vibration type : A Time : 2 hrs each in X,Y, and Z directions Total: 6 hrs Frequency range : 10 to 55 to 10Hz (/min.) Amplitude : 1.5 mm (shall not exceed acceleration 196m/s^2) Mounting method : Soldering onto PC board

7. Solderability

Specified Value	90% or more of immersed surface of terminal electrode shall be covered with fresh solder.
Test Methods and Remarks	Solder temperature : 230±5℃ Immersion time : 4±1 sec. Preconditioning : Immersion into flux. Immersion and Removal speed : 25mm/sec.

8. Resistance to Soldering Heat

Specified Value	Appearance : No significant abnormality Impedance change : Within ±30% of the initial value
Test Methods and Remarks	Preheating : 150℃ for 3 min. Resistance to Soldering Heat : 260±5℃ Duration : 10±0.5 sec. Preconditioning : Immersion into flux. Immersion and Removal speed : 25mm/sec. Recovery : 2 to 3 hrs of recovery under the standard condition after the test.

9. Thermal Shock

Specified Value

Appearance : No significant abnormality
Impedance change : Within＋50/－10% of the initial value

Test Methods and Remarks

According to JIS C60068-2-14.
Conditions for 1 cycle

Step	Temperature (℃)	Duration (min.)
1	－40±3℃	30±3
2	Room Temperature	Within 3
3	85±2℃	30±3
4	Room Temperature	Within 3

Number of cycles : 100
Mounting method : Soldering onto PC board
Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.

10. Resistance to Humidity (steady state)

Specified Value

Appearances : No significant abnormality
Impedance change : Within ±30% of the initial value

Test Methods and Remarks

Temperature : 40±2℃
Humidity : 90 to 95% RH
Duration : 500＋24/－0
Mounting method : Soldering onto PC board
Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.

11. Loading under Damp Heat

Specified Value

Appearance No significant abnormality
Impedance change Within ±30% of the initial value

Test Methods and Remarks

Temperature : 40±2℃
Humidity : 90 to 95%RH
Applied current : Rated current
Duration : 500＋24/－0 hrs
Mounting method : Soldering onto PC board
Recovery : 2 to 3hrs of recovery under the standard condition after the removal from test chamber.

12. High Temperature Loading Test

Specified Value

Appearance : No significant abnormality
Impedance change : Within ±30% of the initial value

Test Methods and Remarks

Temperature : 85±2℃
Duration : 500＋24/－0 hrs
Applied current : Rated current
Mounting method : Soldering onto PC board
Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.

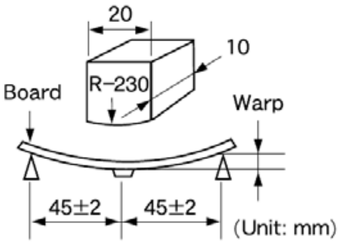
13. Bending Strength

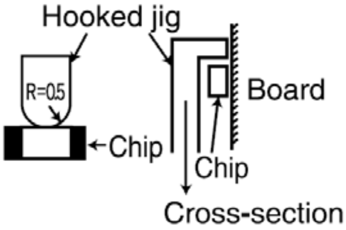
Specified Value

Appearance : No mechanical damage.

Test Methods and Remarks

Warp : 2mm
Testing board : Glass epoxy-resin substrate
Thickness : 0.8mm



14. Adhesion of Electrode	
Specified Value	No separation or indication of separation of electrode.
Test Methods and Remarks	Applied force : 5N Duration : 10 sec. 

Note on standard condition: "standard condition" referred to herein is defined as follows:
5 to 35℃ of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.
When there are questions concerning measurement results:
In order to provide correlation data, the test shall be conducted under condition of 20±2℃ of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition."

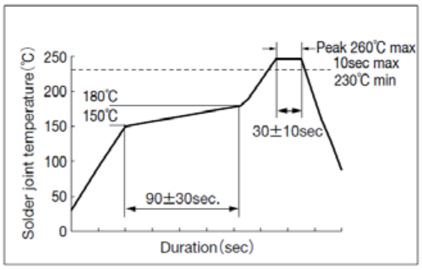
CHIP BEAD INDUCTORS FOR POWER LINE（FB SERIES M TYPE）

PRECAUTIONS

1. Circuit Design	
Precautions	◆Operating environment 1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance. ◆Rated current 1. Rated current of this product is shown in this catalogue, but please be sure to have the base board designed with adequate inspection in case of the generation of heat becomes high within the rated current range when the base board is in high resistance or in bad heating conditions.

2. PCB Design	
Precautions	◆Land pattern design 1. Please refer to a recommended land pattern.

3. Considerations for automatic placement	
Precautions	◆Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.
Technical considerations	◆Adjustment of mounting machine 1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering	
Precautions	◆Wave soldering 1. Please refer to the specifications in the catalog for a wave soldering. ◆Reflow soldering 1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. ◆Lead free soldering 1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, etc. sufficiently. ◆Preheating when soldering Heating : The temperature difference between soldering and remaining heat should not be greater than 150℃. Cooling : The temperature difference between the components and cleaning process should not be greater than 100℃. ◆Recommended conditions for using a soldering iron Put the soldering iron on the land-pattern. Soldering iron's temperature - Below 350℃ Duration - 3 seconds or less The soldering iron should not directly touch the inductor.
Technical considerations	◆Wave, Reflow, Lead free soldering 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. 【Recommended reflow condition】  ◆Preheating when soldering 1. There is a case that products get damaged by a heat shock. ◆Recommended conditions for using a soldering iron 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

5. Handling	
Precautions	◆Handling 1. Keep the inductors away from all magnets and magnetic objects. ◆Setting PC boards 1. When setting a chip mounted base board, please make sure that there is no residual stress to the chip by distortion in the board or at screw part. ◆Breakaway PC boards (splitting along perforations) 1. When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆Mechanical considerations 1. Please do not give the inductors any excessive mechanical shocks.
Technical considerations	◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Setting PC boards 1. There is a case that a characteristic varies with residual stress. ◆Breakaway PC boards (splitting along perforations) 1. Planning pattern configurations and the position of products should be carefully performed to minimize stress. ◆Mechanical considerations 1. There is a case to be damaged by a mechanical shock.

6. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. ・Recommended conditions Ambient temperature −5～40℃ Humidity Below 70% RH The ambient temperature must be kept below 30℃. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, inductors should be used within 6 months from the time of delivery.
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.